

In the Claims

Please amend the claims as follows:

1-21 (Cancelled).

22. (previously presented). The multilayered substrate for a semiconductor device of claim 1, wherein the reinforcing sheet joined to the face for mounting a semiconductor element thereon is in the form of a frame made of a metal, and the frame is formed by etching a metal sheet on which the multilayered substrate body is formed so as to remove the metal material in the region where a semiconductor element is to be mounted.

23. (Previously presented). The multilayered substrate for a semiconductor device of claim 22, wherein the reinforcing sheet comprises aluminum.

24. (Previously presented). The multilayered substrate for a semiconductor device of claim 22, wherein the reinforcing sheet comprises copper.

25. (Previously presented). The multilayered substrate for a semiconductor device of claim 22, wherein the reinforcing sheet comprises a nickel film.

26. (Previously presented). The multilayered substrate for a semiconductor device of claim 22, wherein the reinforcing sheet metal is treated to provide electrical insulation thereon.